



N-CHANNEL ENHANCEMENT MODE MOSFET WITH SCHOTTKY DIODE

### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub> max T <sub>A</sub> = +25°C	
30V	15mΩ @ V <sub>GS</sub> = 10V	10.7A	
307	18.5mΩ @ V <sub>GS</sub> = 4.5V	9.6A	

### Description

This new generation MOSFET is designed to minimize the on-state resistance  $(R_{DS(on)})$  yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

## **Applications**

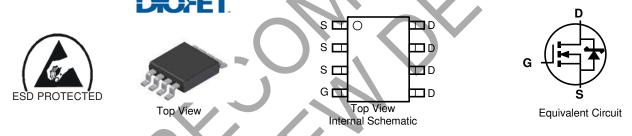
- DC-DC Converters
- Power Management Functions

### Features

- DIOFET Utilizes a Unique Patented Process to Monolithically Integrate a MOSFET and a Schottky in a Single Die to Deliver:
  - Low R<sub>DS(ON)</sub>—Minimizes Conduction Losses
  - Low V<sub>SD</sub>—Reduces Losses due to Body Diode Conduction
  - Low Q<sub>rr</sub>—Lower Q<sub>rr</sub> of the Integrated Schottky Reduces Body Diode Switching Losses
  - Low Gate Capacitance (Qg/Qgs) Ratio—Reduces Risk of SHOOT-THROUGH or Cross Conduction Currents at High Frequencies
  - Avalanche Rugged—I<sub>AR</sub> and E<sub>AR</sub> Rated
- ESD Protected
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

### **Mechanical Data**

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
  - Moisture Sensitivity: Level 1 per J-STD-020
  - Terminal Connections: See Diagram Below
- Weight: 0.072 grams (approximate)



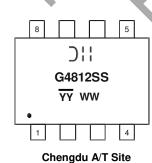
### Ordering Information (Note 4)

Part Number         Case         Packaging           DMG4812SSS-13         SO-8         2500/Tape & Reel			
DMG4812SSS-13 SO-8 2500/Tape & Reel	Part Number	Case	Packaging
	DMG4812SSS-13		2500/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  - 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.</p>
  - . For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## Marking Information



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Shanghai A/T Site

)' | = Manufacturer's Marking
G4812SS = Product Type Marking Code
YYWW = Date Code Marking
YY or YY = Year (ex: 13 = 2013)
WW = Week (01 - 53)
YY = Date Code Marking for SAT (Shanghai Assembly/ Test site)
YY = Date Code Marking for CAT (Chengdu Assembly/ Test site)



Unit

W

°C/W

# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Character	Symbol	Value	Unit		
Drain-Source Voltage			V <sub>DSS</sub>	30	V
Gate-Source Voltage			V <sub>GSS</sub>	±12	V
Continuous Drain Current (Note 5) $V_{GS}$ = 10V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +85°C	Ι <sub>D</sub>	8 6.4	А
Continuous Drain Current (Note 6) $V_{GS} = 10V$	$t \leq 10 \; \text{sec}$	T <sub>A</sub> = +25°C T <sub>A</sub> = +85°C	ID	10.7 8.6	А
Continuous Drain Current (Note 6) $V_{GS}$ = 4.5V	$t \leq 10 \; \text{sec}$	T <sub>A</sub> = +25°C T <sub>A</sub> = +85°C	ID	9.6 7.7	А
Pulsed Drain Current (Note 7)			I <sub>DM</sub>	45	А
Avalanche Current (Notes 7 & 8)			l <sub>AR</sub>	13	А
Repetitive Avalanche Energy (Notes 7 & 8) L = 0.3mH			E <sub>AR</sub>	25.4	mJ

# Characteristics Symbol Value Power Dissipation (Note 5) PD 1,54 Thermal Resistance, Junction to Ambient @TA = +25°C (Note 5) ReJA 81

Power Dissipation (Note 6)	PD	2.8	W
Thermal Resistance, Junction to Ambient $@T_A = +25^{\circ}C$ (Note 6)	R <sub>0JA</sub>	45	°C/W
Operating and Storage Temperature Range	TJ, T <sub>STG</sub>	-55 to +150	°C

# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

			_				
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30		_	V	$V_{GS} = 0V, I_D = 1mA$	
Zero Gate Voltage Drain Current	IDSS	—	—	150	μA	$V_{DS} = 30V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	Ι	—	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	1.0	_	2.3	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
Static Drain-Source On-Besistance	D		11	15	mΩ	$V_{GS} = 10V, I_D = 10.7A$	
Static Drain-Source On-nesistance	RDS (ON)	I	16.5	18.5	11152	$V_{GS} = 4.5V, I_D = 9.6A$	
Forward Transfer Admittance	Y <sub>fs</sub>		20		S	$V_{DS} = 5V, I_D = 10.7A$	
Diode Forward Voltage	V <sub>SD</sub>		0.36	0.5	V	$V_{GS} = 0V, I_{S} = 1A$	
Maximum Body-Diode + Schottky Continuous Current	l <sub>S</sub>		—	5	А	—	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	Ciss	—	1849	_	pF		
Output Capacitance	Coss	_	158	_	pF	V <sub>DS</sub> =15V, V <sub>GS</sub> = 0V, f = 1.0MHz	
Reverse Transfer Capacitance	Crss	—	123	_	pF		
Gate Resistance	R <sub>q</sub>	0.54	2.0	4.0	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	
Total Gate Charge V <sub>GS</sub> = 4.5V	Qq	_	18.5	_	nC		
Total Gate Charge V <sub>GS</sub> = 10V	Qg	_	43	_	nC	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 10V,	
Gate-Source Charge	Q <sub>qs</sub>	_	4.7	_	nC	I <sub>D</sub> = 9.6A	
Gate-Drain Charge	Q <sub>gd</sub>	_	4.0	_	nC		
Turn-On Delay Time	t <sub>D(on)</sub>	—	6.62	_	ns		
Turn-On Rise Time	tr	_	8.73	_	ns	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 15V,	
Turn-Off Delay Time	t <sub>D(off)</sub>	_	36.41		ns	$R_G = 3\Omega, R_L = 15\Omega, I_D = 1A$	
Turn-Off Fall Time	t <sub>f</sub>	_	4.69		ns		

Notes:

5. Device mounted on FR-4 PCB with minimum recommended pad layout. The value in any given application depends on the user's specific board design. 6. Device mounted on  $1" \times 1"$  FR-4 PCB with high coverage 1 oz. Copper, single sided, device is measured at t  $\leq$  10 sec.

7. Repetitive rating, pulse width limited by junction temperature.

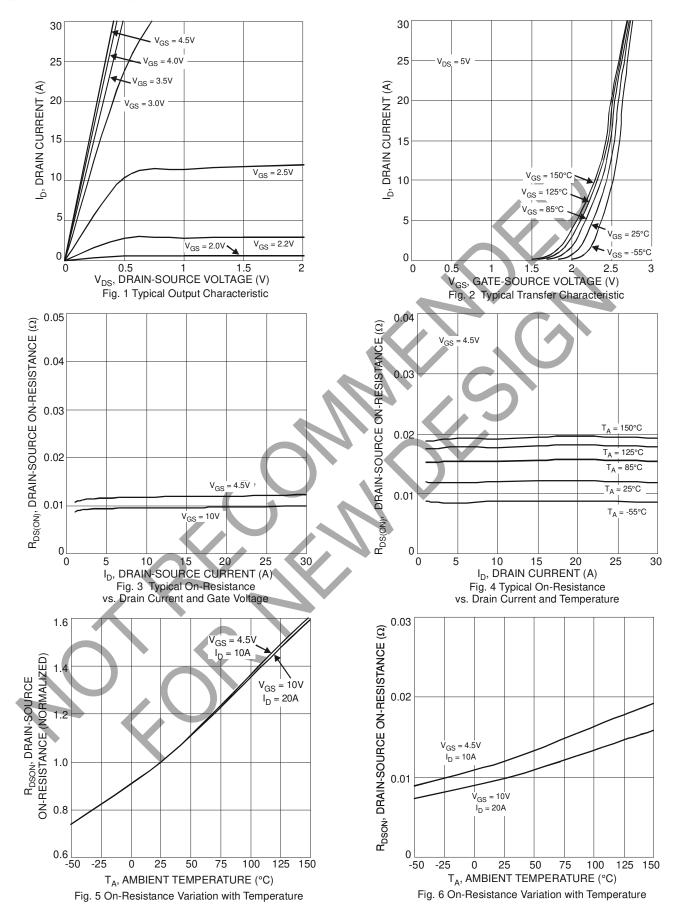
8. I<sub>AR</sub> and E<sub>AR</sub> rating are based on low frequency and duty cycles to keep  $T_J = +25^{\circ}C$ 

9. Short duration pulse test used to minimize self-heating effect.

10. Guaranteed by design. Not subject to production testing.

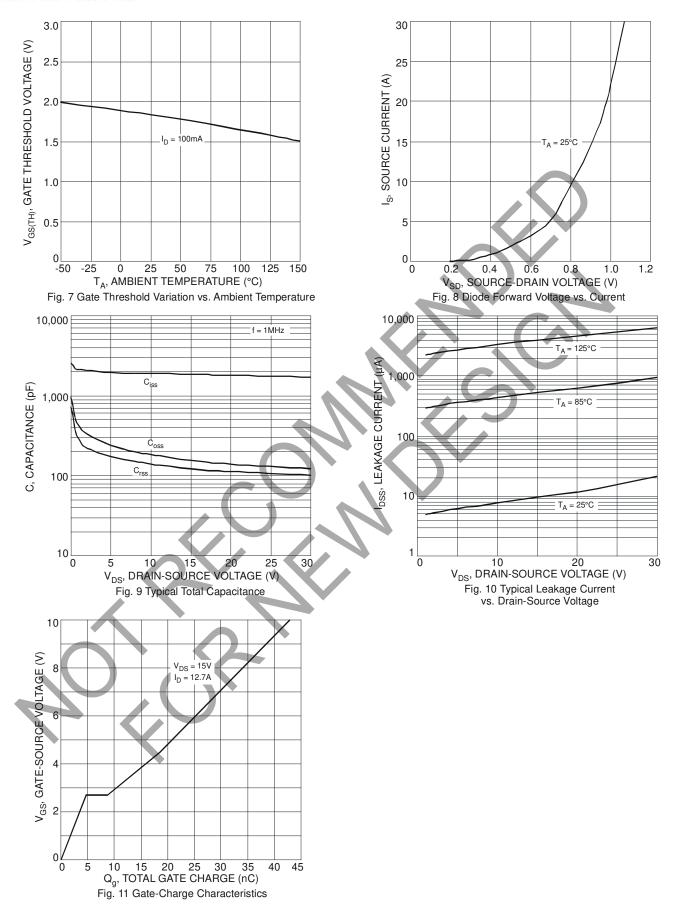


# **DMG4812SSS**

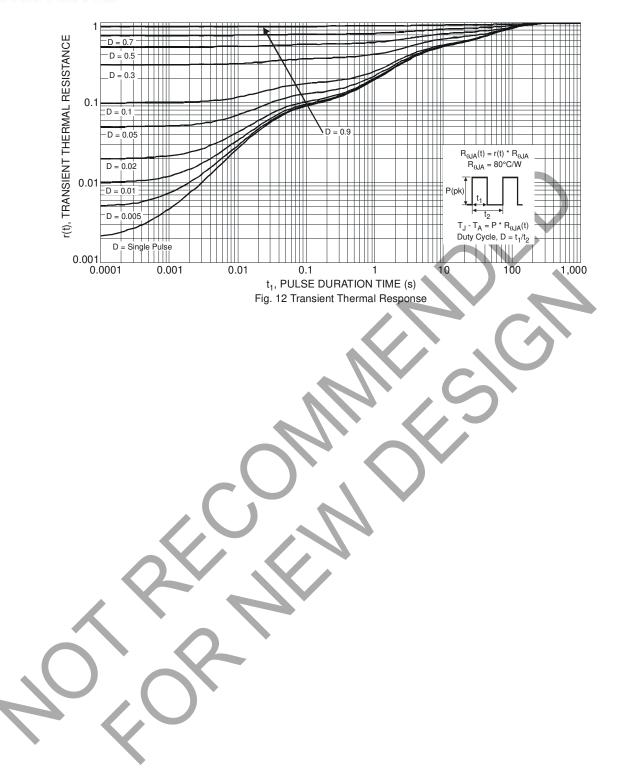




# **DMG4812SSS**



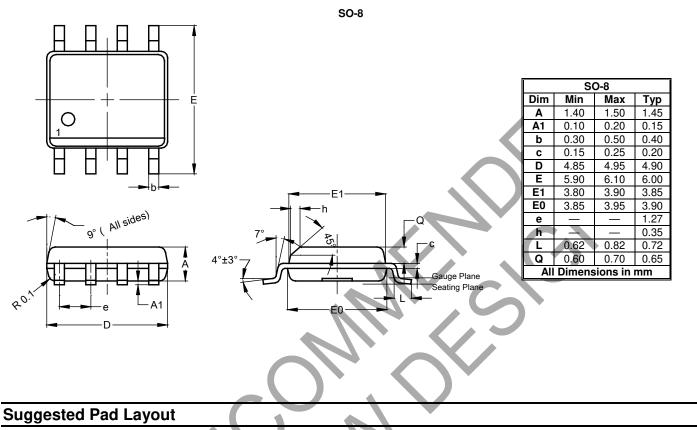




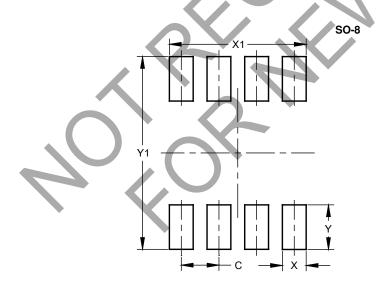


# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version



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Dimensions	Value (in mm)
С	1.27
Х	0.802
X1	4.612
Y	1.505
Y1	6.50



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